

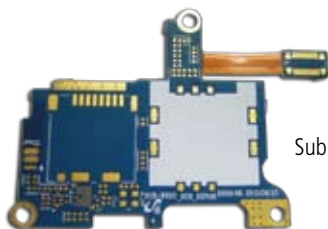
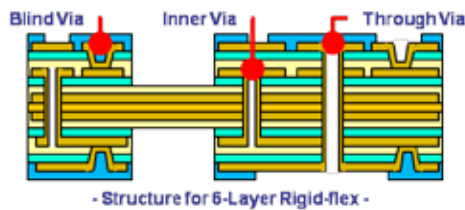
Total Flexible Printed Circuit Solutions for Mobile Phones

Jabil | Green Point and SI Flex are collaborating to provide mobile OEMs a one-stop-solution for components and flexible circuits, avoiding the drawbacks of multiple component interaction:

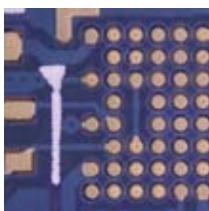
- Accelerated time to market;
- Simplified supply chain management;
- Improved manufacturing and material solutions.

RIGID FLEX WITH 0.4 PITCH CSP

- 6-Layer rigid-flex
- 0.4 pitch CSP
- Blind via holes (layer 1 through layer 2, layer 5 through layer 6)
- Inner via holes (layer 2 through layer 5)
- Surface Treatment: ENIG



Sub Board for Usim Card



0.4pitch CSP



Blind Via



Inner Via

For more information, please contact

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Applications

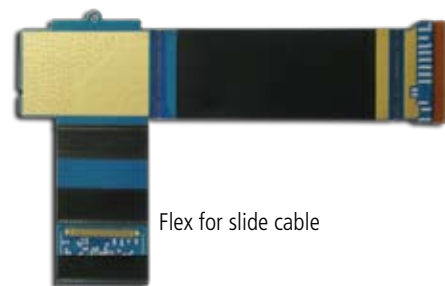
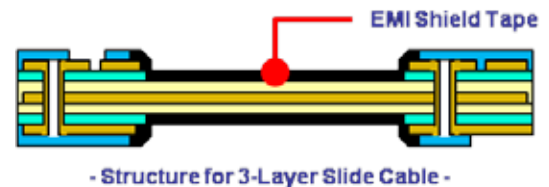
- LCD module flex
- Camera module flex
- Key pad flex
- Touch screen flex
- Slide cable flex
- Hinge flex
- Sub board (rigid flex)
- Battery flex

Products

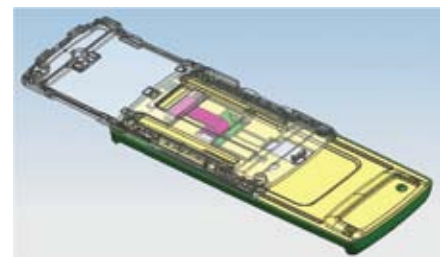
- Single-sided flex
- Double-sided flex
- Multi layer board (3~6 layers)
- Rigid flex board (3~6 layers)

DYNAMIC CHARACTERISTICS FOR SLIDE CABLE

- 3-Layer rigid-flex with EMI shield
- Pattern width & space: 70um & 70um
- Surface treatment: direct Au
- Standard for sliding test: +200,000 times of sliding



Flex for slide cable



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HIGH DENSITY CIRCUIT BY ROLL TO ROLL PROCESS

Advantages

- High yield manufacturing
- Minimum defect rate - reducing handling process
- High density pattern capability
- Ultra thin flex manufacturing
- Applying micro via hole



Laser Drilling



Copper Plating

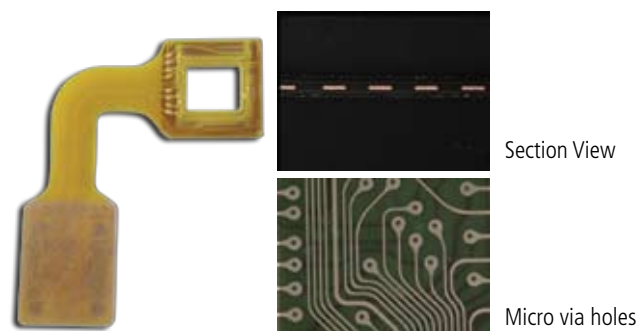


Exposure



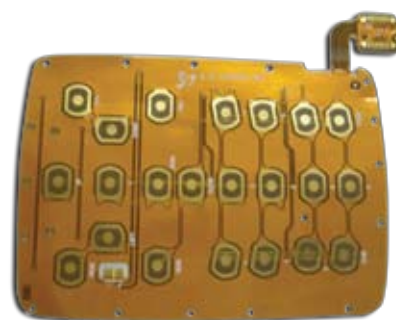
Etching

HIGH DENSITY CAMERA MODULE FLEX



- Easy design for flex
- Minimize flex size
- Pattern width & space: 40 um 40 um
- Micro via holes
 - Via diameter: 50 um
 - Via pad diameter: 160 um

ULTRA THIN KEY PAD FLEX



- Appropriate for ultra thin cellular phone
- Thickness of flex: $\leq 0.15\text{mm}$